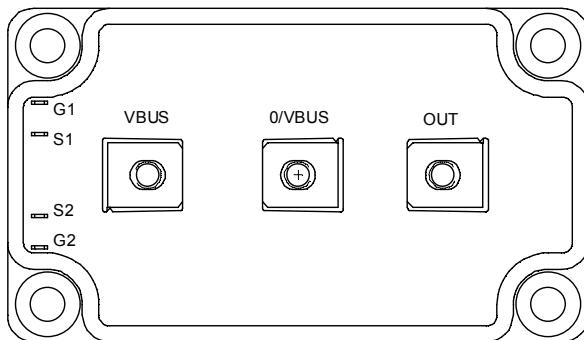
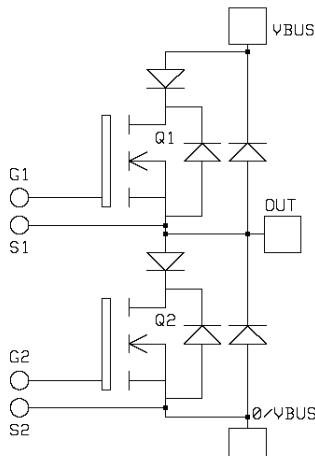


**Phase leg
Series & SiC parallel diodes
Super Junction
MOSFET Power Module**

**V_{DSS} = 600V
R_{DSon} = 18mΩ max @ T_j = 25°C
I_D = 143A @ T_c = 25°C**



Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V _{DSS}	Drain - Source Breakdown Voltage	600	V
I _D	Continuous Drain Current	T _c = 25°C T _c = 80°C	143 107
I _{DM}	Pulsed Drain current		
V _{GS}	Gate - Source Voltage	±30	V
R _{DSon}	Drain - Source ON Resistance	18	mΩ
P _D	Maximum Power Dissipation	T _c = 25°C	833
I _{AR}	Avalanche current (repetitive and non repetitive)		
E _{AR}	Repetitive Avalanche Energy	1	mJ
E _{AS}	Single Pulse Avalanche Energy	1800	

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handing Procedures Should Be Followed.

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
BV_{DSS}	Drain - Source Breakdown Voltage	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 1000\mu\text{A}$	600			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 600\text{V}$	$T_j = 25^\circ\text{C}$		100	μA
		$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 600\text{V}$	$T_j = 125^\circ\text{C}$		1000	
$R_{\text{DS(on)}}$	Drain – Source on Resistance	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 71.5\text{A}$			18	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}} = V_{\text{DS}}, I_{\text{D}} = 4\text{mA}$	2.1	3	3.9	V
I_{GSS}	Gate – Source Leakage Current	$V_{\text{GS}} = \pm 20\text{ V}, V_{\text{DS}} = 0\text{V}$			± 200	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{\text{GS}} = 0\text{V}$ $V_{\text{DS}} = 25\text{V}$ $f = 1\text{MHz}$		28		nF
C_{oss}	Output Capacitance			10.2		
C_{rss}	Reverse Transfer Capacitance			0.85		
Q_g	Total gate Charge	$V_{\text{GS}} = 10\text{V}$ $V_{\text{Bus}} = 300\text{V}$ $I_{\text{D}} = 143\text{A}$		1036		nC
Q_{gs}	Gate – Source Charge			116		
Q_{gd}	Gate – Drain Charge			444		
$T_{\text{d(on)}}$	Turn-on Delay Time	Inductive switching @ 125°C $V_{\text{GS}} = 15\text{V}$ $V_{\text{Bus}} = 400\text{V}$ $I_{\text{D}} = 143\text{A}$ $R_G = 1.2\Omega$		21		ns
T_r	Rise Time			30		
$T_{\text{d(off)}}$	Turn-off Delay Time			283		
T_f	Fall Time			84		
Eon	Turn-on Switching Energy	Inductive switching @ 25°C $V_{\text{GS}} = 15\text{V}, V_{\text{Bus}} = 400\text{V}$ $I_{\text{D}} = 143\text{A}, R_G = 1.2\Omega$		1608		μJ
Eoff	Turn-off Switching Energy ①			3920		
Eon	Turn-on Switching Energy	Inductive switching @ 125°C $V_{\text{GS}} = 15\text{V}, V_{\text{Bus}} = 400\text{V}$ $I_{\text{D}} = 143\text{A}, R_G = 1.2\Omega$		2630		μJ
Eoff	Turn-off Switching Energy ①			4824		

① In accordance with JEDEC standard JESD24-1.

Series diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$I_{\text{F(AV)}}$	Maximum Average Forward Current	50% duty cycle	$T_c = 85^\circ\text{C}$		120	
V_F	Diode Forward Voltage	$I_F = 120\text{A}$		1.1	1.15	V
		$I_F = 240\text{A}$		1.4		
		$I_F = 120\text{A}$	$T_j = 125^\circ\text{C}$	0.9		
t_{rr}	Reverse Recovery Time	$I_F = 120\text{A}$	$T_j = 25^\circ\text{C}$		31	ns
		$V_R = 133\text{V}$ $di/dt = 400\text{A}/\mu\text{s}$	$T_j = 125^\circ\text{C}$		60	
Q_{rr}	Reverse Recovery Charge	$I_F = 120\text{A}$	$T_j = 25^\circ\text{C}$		120	nC
		$V_R = 133\text{V}$ $di/dt = 400\text{A}/\mu\text{s}$	$T_j = 125^\circ\text{C}$		500	

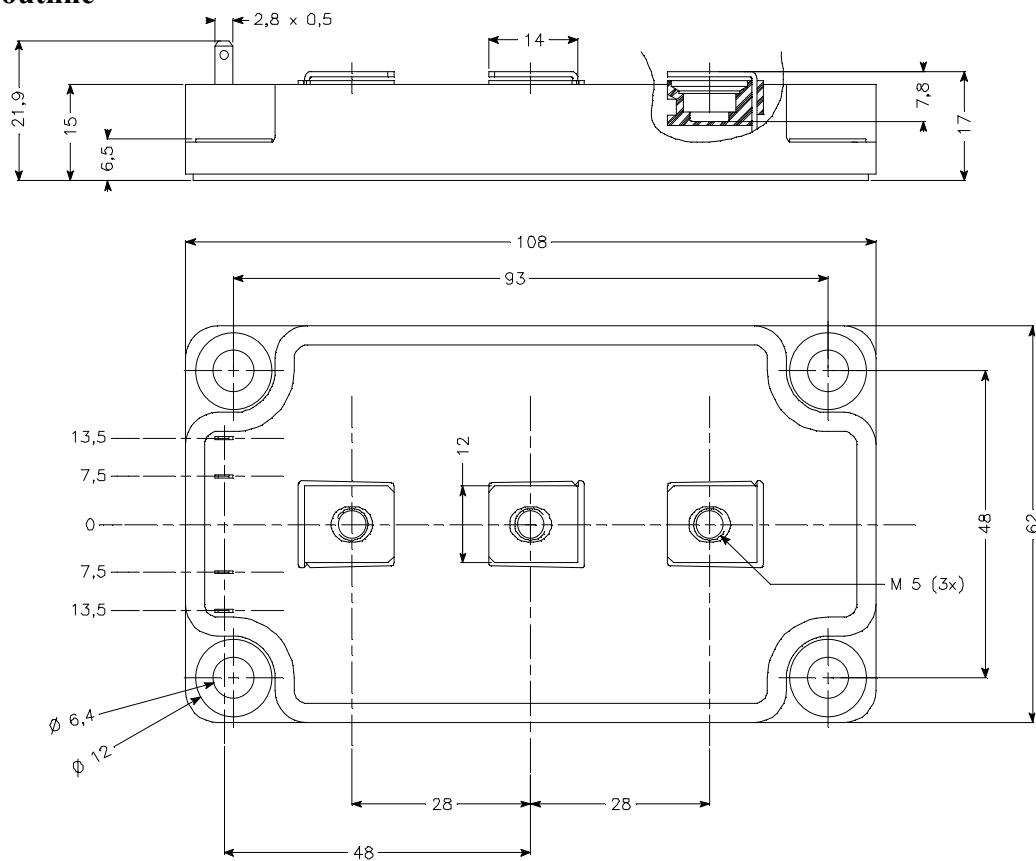
Parallel diode ratings and characteristics

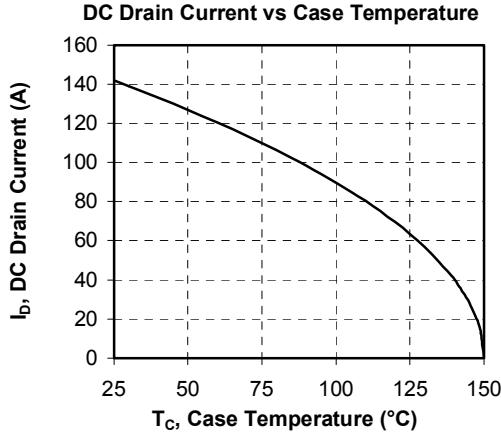
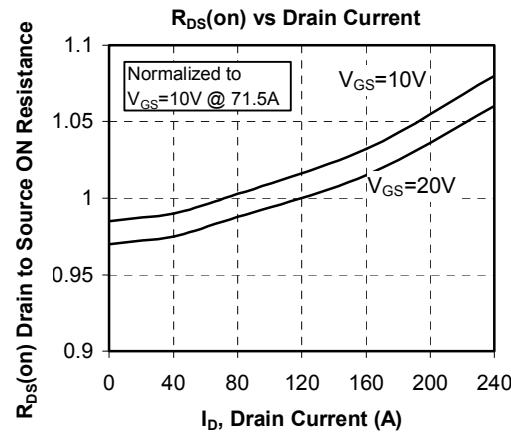
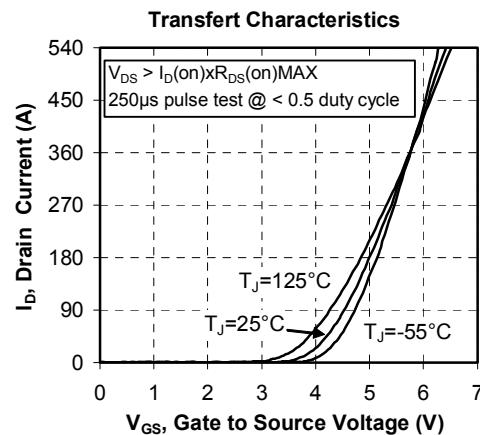
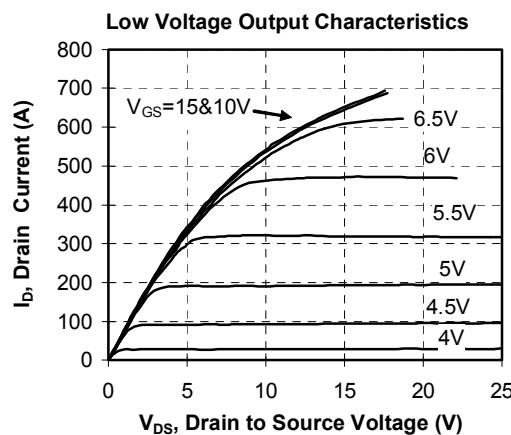
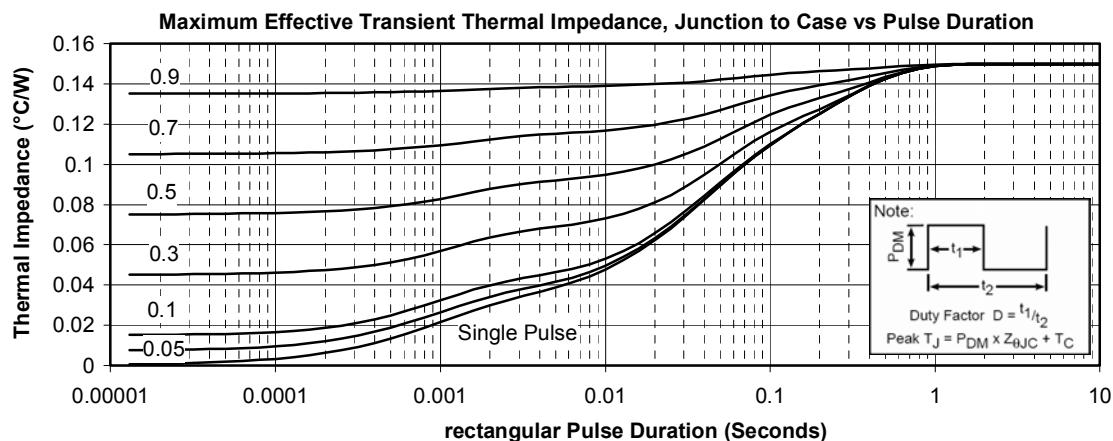
Symbol		Characteristic		Test Conditions		Min	Typ	Max	Unit
$I_{F(AV)}$		Maximum Average Forward Current		50% duty cycle		$T_c = 125^\circ C$		80	A
V_F	Diode Forward Voltage		$I_F = 80A$	$T_j = 25^\circ C$			1.6	1.8	V
				$T_j = 175^\circ C$			2.0	2.4	
Q_C	Total Capacitive Charge		$I_F = 80A, V_R = 300V$ $di/dt = 2000A/\mu s$				112		nC
Q	Total Capacitance		$f = 1MHz, V_R = 200V$				520		pF
			$f = 1MHz, V_R = 400V$				400		

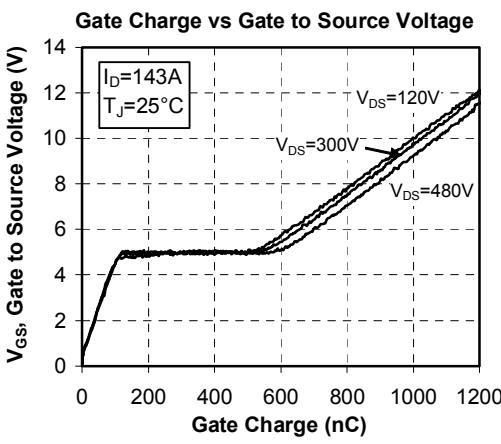
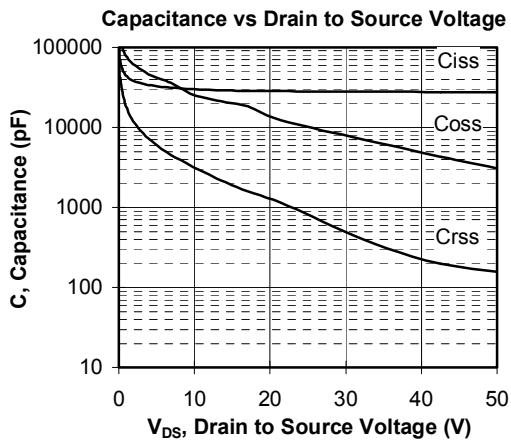
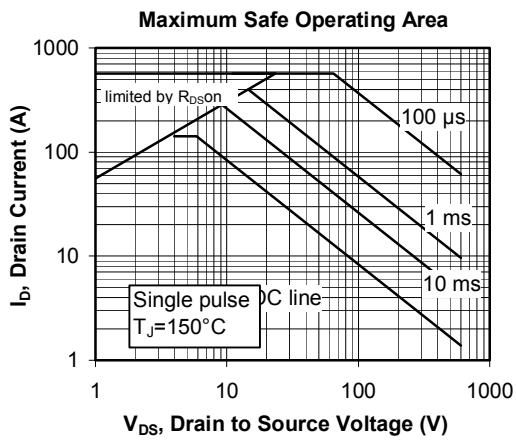
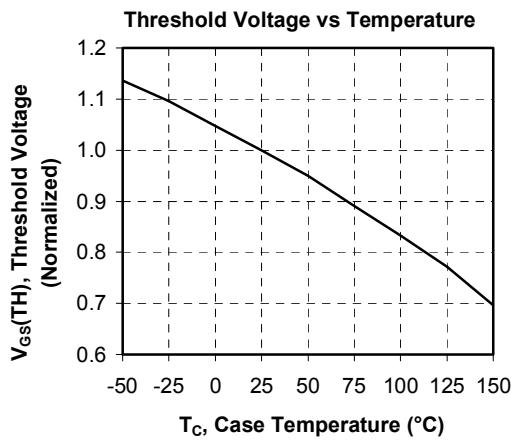
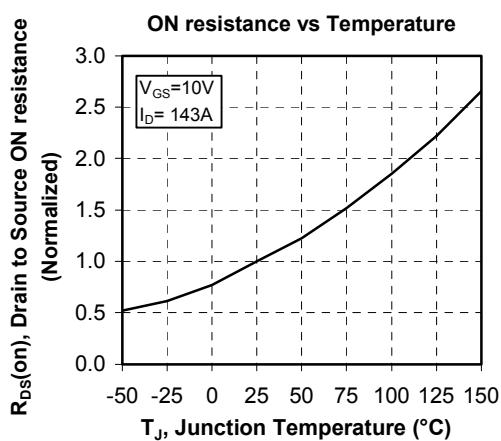
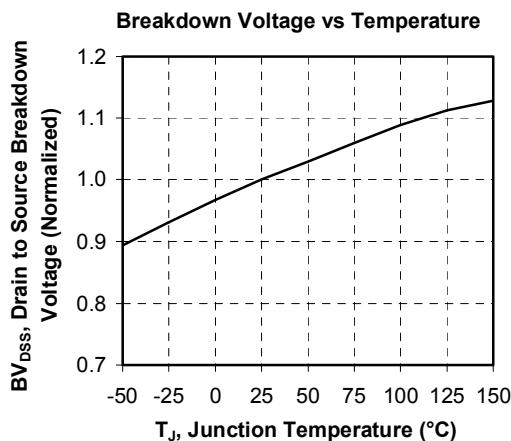
Thermal and package characteristics

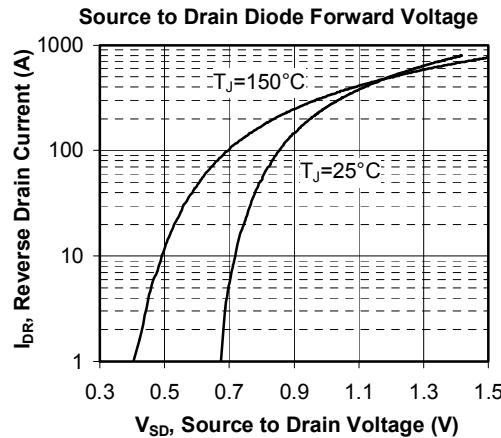
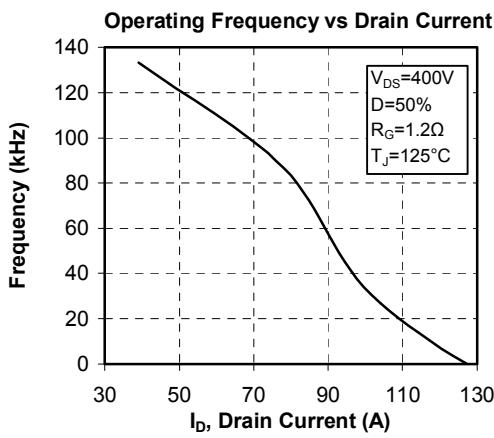
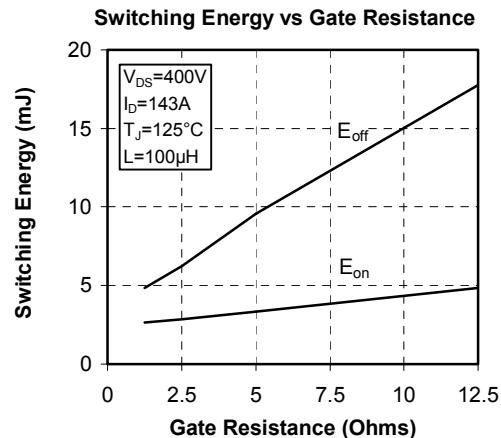
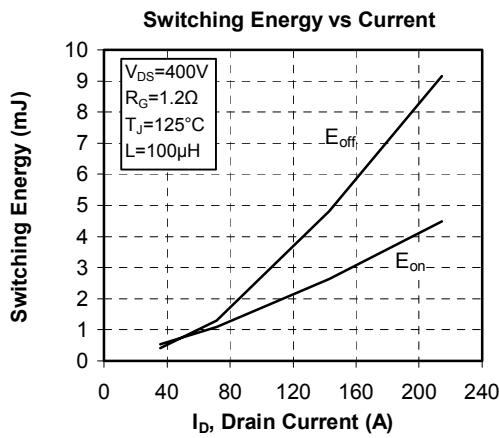
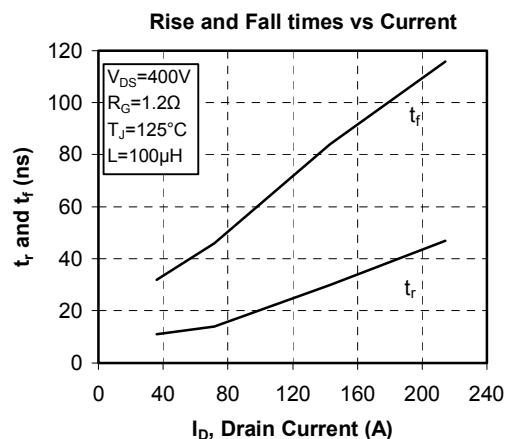
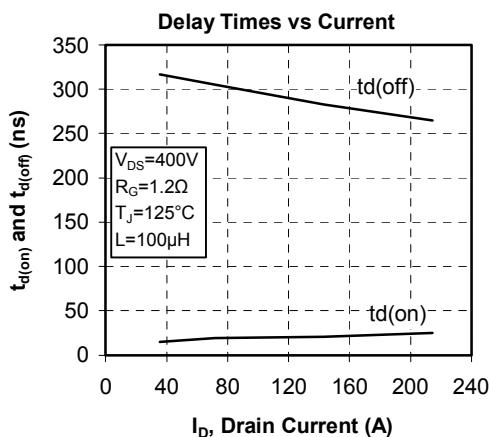
Symbol Characteristic		Min	Typ	Max	Unit
R_{thJC}	Junction to Case	Transistor			0.15
		Series diode			0.46
		Parallel diode			0.35
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, $I_{isol} < 1\text{mA}$, 50/60Hz		2500		V
T_J	Operating junction temperature range		-40		150
T_{STG}	Storage Temperature Range		-40		125
T_C	Operating Case Temperature		-40		100
Torque	Mounting torque	To heatsink	M6	3	5
		For terminals	M5	2	3.5
Wt	Package Weight				280 g

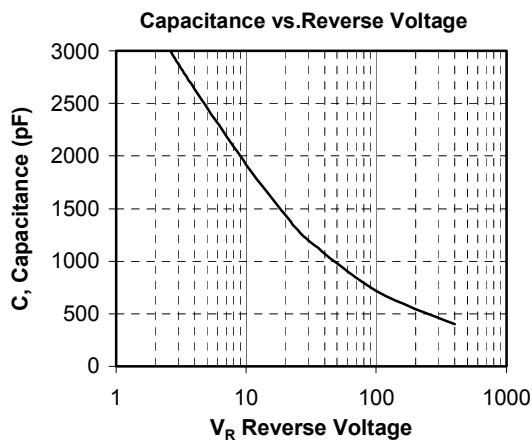
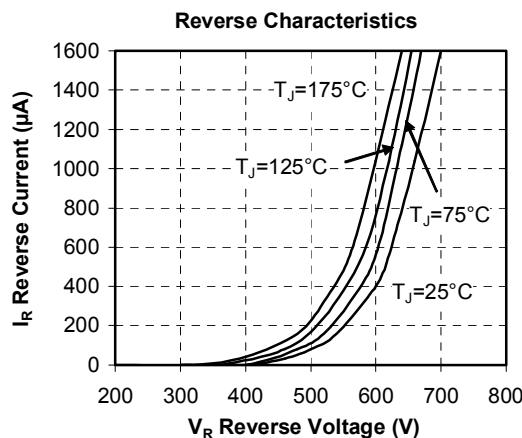
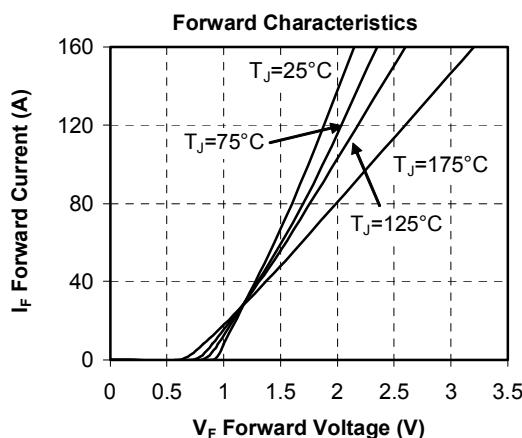
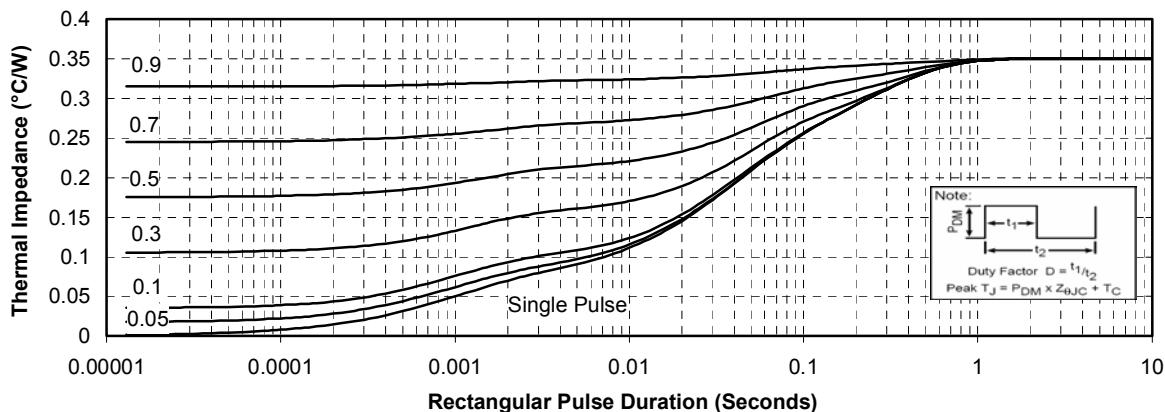
Package outline



Typical CoolMOS Performance Curve






Typical SiC Diode Performance Curve
Maximum Effective Transient Thermal Impedance, Junction to Case vs Pulse Duration


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